Variant: 001 Generated: 9/2/2015 3:16:35 PM TID #: TIDA-00656



TIDA-00656 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C2	2	4.7uF	C2012X5R1H475K125AB	TDK	CAP, CERM, 4.7uF, 50V, +/-10%, X5R, 0805	0805
2	C3	1	10uF	C1608X5R1A106M	TDK	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603
3	C4, C10, C11	3	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
4	C5, C6	2	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
5	C7, C8	2	1uF	C1608X5R1E105K080AC	TDK	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0603	0603
6	C9	1	1000pF	06035A102KAT2A	AVX	CAP, CERM, 1000pF, 50V, +/-10%, C0G/NP0, 0603	0603
7	C12	1	2200pF	06031C222JAT2A	AVX	CAP, CERM, 2200pF, 100V, +/-5%, X7R, 0603	0603
8	H1, H2, H3, H4	4		SJ5382	3M	Bumpon, Hemisphere, 0.25 X 0.075, Clear	75x250 mil
9	J1	1		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
10	J2	1		ED120/3DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 3POS, TH	TERM_BLK, 3pos, 5.08mm
11	J3	1		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
12	J4	1		TSW-104-07-G-S	Samtec	Header, TH, 100mil, 4x1, Gold plated, 230 mil above insulator	4x1 Header
13	L1	1	47uH	CB2518T470K	Taiyo Yuden	Inductor, Wirewound, Ferrite, 47uH, 0.11A, 1.235 ohm, SMD	2.5x1.8x1.8mm
14	R1	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	0603
15	R2	1	24.3k	CRCW060324K3FKEA	Vishay-Dale	RES, 24.3 k, 1%, 0.1 W, 0603	0603
16	R3, R4, R5, R8, R9	5	4.75k	CRCW06034K75FKEA	Vishay-Dale	RES, 4.75k ohm, 1%, 0.1W, 0603	0603
17	R6	1	2.43k	CRCW06032K43FKEA	Vishay-Dale	RES, 2.43 k, 1%, 0.1 W, 0603	0603
18	R7	1	47.0k	RG1608P-473-B-T5	Susumu Co Ltd	RES, 47.0k ohm, 0.1%, 0.1W, 0603	0603
19	U1	1		DRV10983PWP	Texas Instruments	12- to 24-V, Three-Phase, Sensorless BLDC Motor Driver, PWP0024B	PWP0024B
20	U2	1		MSP430G2303IPW20	Texas Instruments	16 MHz Mixed Signal Microcontroller with 4 KB Flash, 256 B SRAM and 24 GPIOs, -40 to 85 degC, 20-pin SOP (PW), Green (RoHS & no Sb/Br)	PW0020A
21	U3	1	TSOP31138	TSOP31138	Vishay	Opto, Infrared Receiver	0.236 X 0.220 inch

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